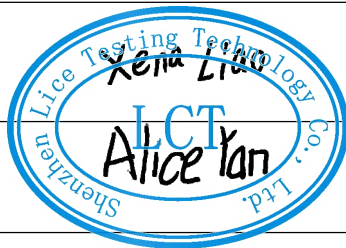




Test Report

Report Number:	LCT-250103290247	
Applicant:	Shenzhen Hao Mai Tongda Technology Co., Ltd.	
Address:	Room703, Building F, Qihang R&D Industrial Park, No.1008, Songbai Road, Sunshine Community, Xili Street, Nanshan District, Shenzhen, China	
Manufacturer:	SHENZHEN SORGHUM RED ELECTRONICS TECHNOLOGY CO Ltd.	
Address:	XINHE RD 29 SHANGMUGU COMMUNITY PINGHU TOWN LONGGANG DISTRICT SHENZHEN, GUANGDONG 518111 CHINA	
Report on the submitted samples said to be:		
Sample Name:	Adapter	
Sample No.:	H3, T8	
Difference:	All models are the same except for the model name	
Brand Name:	N/A	
Receipt Date:	2025-01-06	
Testing Period:	2025-01-06 to 2025-01-17	
Date of Issue:	2025-01-17	
Results:	Please refer to next page(s).	
Test/Witness Engineer:	Xena Liao	
Approved & Authorized:	Alice Yan	
Shenzhen LCT Testing Technology Co., Ltd. Room 112-113, Building B15, Yintian Industrial Zone, Yantian, Xixiang Street, Bao'an District, Shenzhen, Guangdong, China		
Test Request		Conclusion
According to the customer's request, based on the performed tests on submitted sample, the result of Lead, Cadmium, Mercury, Hexavalent Chromium, PBBs, PBDEs, Dibutyl Phthalate(DBP), Benzylbutyl Phthalate(BBP), Bis(2-ethylhexyl) Phthalate(DEHP), Diisobutyl phthalate(DIBP) content comply with the limit as set of RoHS Directive (EU) 2015/863 amending Annex II to Directive 2011/65/EU.		Pass

The test results of this report relate only to the tested sample identified in this report. It is incumbent on the manufacturer to assure the constant quality of the product. This report shall not be reproduced, except in full, without the written approval of the Issuing Testing Laboratory

Results:**A. EU RoHS Directive 2011/65/EU and its amendment directives on XRF**

Test method: With reference to IEC 62321-3-1:2013, Screening by X-ray Fluorescence Spectroscopy (XRF)

Seq. No.	Tested Part(s)	Results					
		Cd	Pb	Hg	Cr ^{VI}	Br ^{VI}	
						PBBs	PBDEs
1	Black plastic casing	BL	BL	BL	BL	BL	BL
2	Metal plug	BL	BL	BL	BL	/	/
3	Copper	BL	BL	BL	BL	/	/
4	Silver plating	BL	BL	BL	BL	/	/
5	USB socket	BL	BL	BL	BL	/	/
6	PCB	BL	BL	BL	BL	BL	BL
7	IC	BL	BL	BL	BL	BL	BL
8	Resistance	BL	BL	BL	BL	BL	BL
9	Electrolytic capacitor	BL	BL	BL	BL	BL	BL
10	Transformer	BL	BL	BL	BL	BL	BL
11	Y capacitor	BL	BL	BL	BL	BL	BL

Note:

- (1) Results were obtained by XRF for primary screening, and further chemical testing by ICP (for Cd, Pb, Hg), UV-Vis (for Cr(VI)) and GC-MS (for PBBs, PBDEs) are recommended to be performed, if the concentration exceeds the below warning value according to IEC 62321-3-1:2013.

Element	Unit	Non-metal	Metal	Composite Material
Cd	mg/kg	$BL \leq 70 - 3\sigma < X < 130 + 3\sigma \leq OL$	$BL \leq 70 - 3\sigma < X < 130 + 3\sigma \leq OL$	$BL \leq 50 - 3\sigma < X < 150 + 3\sigma \leq OL$
Pb	mg/kg	$BL \leq 700 - 3\sigma < X < 1300 + 3\sigma \leq OL$	$BL \leq 700 - 3\sigma < X < 1300 + 3\sigma \leq OL$	$BL \leq 500 - 3\sigma < X < 1500 + 3\sigma \leq OL$
Hg	mg/kg	$BL \leq 700 - 3\sigma < X < 1300 + 3\sigma \leq OL$	$BL \leq 700 - 3\sigma < X < 1300 + 3\sigma \leq OL$	$BL \leq 500 - 3\sigma < X < 1500 + 3\sigma \leq OL$
Cr	mg/kg	$BL \leq 700 - 3\sigma < X$	$BL \leq 700 - 3\sigma < X$	$BL \leq 500 - 3\sigma < X$
Br	mg/kg	$BL \leq 300 - 3\sigma < X$	--	$BL \leq 250 - 3\sigma < X$

Note:

BL = Below Limit
 OL = Over Limit
 X = Inconclusive

- (2) The XRF screening test for RoHS elements – The reading may be different to the actual content in the sample be of non-uniformity composition.
- (3) The maximum permissible limit is quoted from the document 2015/863/EC amending RoHS directive 2011/65/EU:
- (4) ▼=For restricted substances PBBs and PBDEs, the results show the total Br content; The restricted substance was Cr(VI), and the results showed the total Cr content

RoHS Restricted Substances	Maximum Concentration Value (mg/kg) (by weight in homogenous materials)
Cadmium (Cd)	100
Lead (Pb)	1000
Mercury (Hg)	1000
Hexavalent Chromium (Cr(VI))	1000
Polybrominated biphenyls (PBBs)	1000
Polybrominated diphenylethers (PBDEs)	1000
Dibutyl Phthalate(DBP)	1000
Benzylbutyl Phthalate(BBP)	1000
Bis(2-ethylhexyl) Phthalate(DEHP)	1000
Diisobutyl phthalate(DIBP)	1000

Disclaimers:

This XRF Screening report is for reference purposes only. The applicant shall make its/his/her own judgment as to whether the information provided in this XRF screening report is sufficient for its/his/her purposes.

The result shown in this XRF screening report will differ based on various factors, including but not limited to, the sample size, thickness, area, surface flatness, equipment parameters and matrix effect (e.g. plastic, rubber, metal, glass, ceramic etc.). Further wet chemical pre-treatment with relevant chemical equipment analysis are required to obtain quantitative data.

B. EU RoHS Directive 2011/65/EU and its amendment Directives 2015/863/EU on Lead, Cadmium, Mercury, Hexavalent Chromium, PBBs, PBDEs, DBP, BBP, DEHP, DIBP content.

Test method:

Lead(Pb) & Cadmium(Cd) Content:

With reference to IEC 62321-5:2013, by acid digestion and analysis was performed by inductively coupled plasma atomic emission spectrometer (ICP-OES)

Mercury(Hg) Content:

With reference to IEC 62321-4:2013+AMD1:2017 CSV, by acid digestion and analysis was performed by inductively coupled plasma atomic emission spectrometer (ICP-OES)

Hexavalent Chromium(Cr^{6+}) Content:

With reference to IEC 62321-7-1:2015 or IEC 62321-7-2:2017, by alkaline digestion and analysis was performed by UV-visible spectrophotometer (UV-Vis)

PBBs & PBDEs Content:

With reference to IEC 62321-6:2015, by solvent extraction and analysis was performed by gas chromatographic-mass spectrometer (GC-MS)

BBP DBP DEHP & DIBP Content:

With reference to IEC 62321-8:2017, by solvent extraction and analysis was performed by gas chromatographic-mass spectrometer (GC-MS)

Note:

- #1 According to RoHS directive 2011/65/EU and its amendments, Lead is exempted in glass of cathode ray tubes, electronic components and fluorescent tubes.
- #2 According to RoHS directive 2011/65/EU and its amendments, Lead is exempted in electronic ceramic parts (e.g. piezoelectronic devices).
- #3 According to RoHS directive 2011/65/EU and its amendments, Lead is exempted as an alloying element in Copper containing up to 4% (40000ppm) by weight.
- #4 According to RoHS directive 2011/65/EU and its amendments, Lead is exempted in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead).
- #5 According to the statement provided by the customer, according to RoHS directive 2011/65/EU and its amendments, Lead is exempted as an alloying element in Aluminum containing up to 0.4% (4000ppm) by weight.
- #6 According to the statement provided by the customer, according to RoHS directive 2011/65/EU and its amendments, Cadmium and its compounds in electrical contact is exempted.
- #7 According to the statement provided by the customer, according to RoHS directive 2011/65/EU and its Amendments, Lead is exempted in steel for machining purposes and in galvanised steel containing up to 0.35% (3500ppm) by weight.

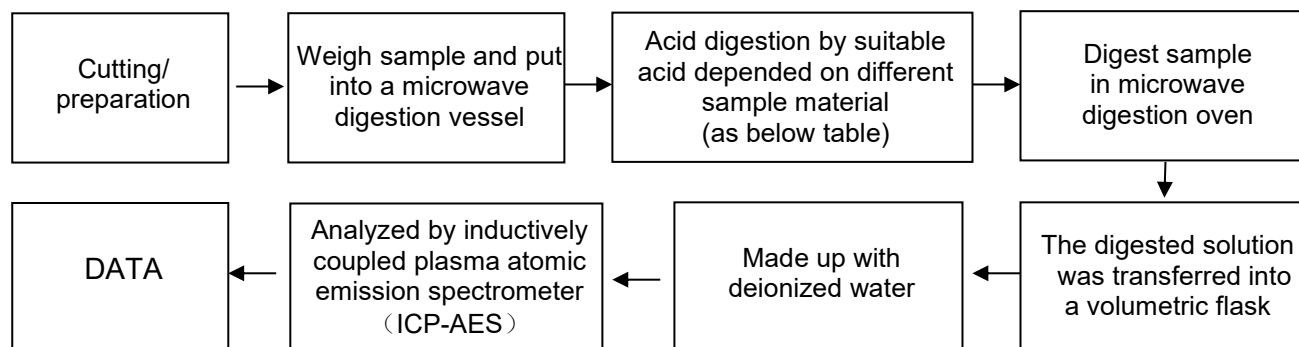
1) The test results of DBP、BBP、DEHP & DIBP

Item	Unit	MDL	Results			Limit
			1	6	7	
Dibutyl Phthalate(DBP)	mg/kg	50	N.D.	N.D.	N.D.	1000
Benzylbutyl Phthalate(BBP)	mg/kg	50	N.D.	N.D.	N.D.	1000
Bis(2-ethylhexyl) Phthalate(DEHP)	mg/kg	50	N.D.	N.D.	N.D.	1000
Diisobutyl phthalate(DIBP)	mg/kg	50	N.D.	N.D.	N.D.	1000

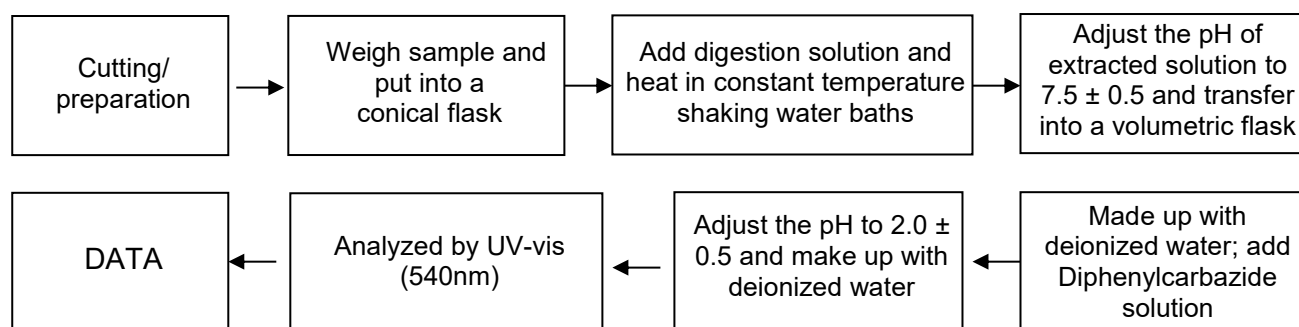
Item	Unit	MDL	Results				Limit
			8	9	10	11	
Dibutyl Phthalate(DBP)	mg/kg	50	N.D.	N.D.	N.D.	N.D.	1000
Benzylbutyl Phthalate(BBP)	mg/kg	50	N.D.	N.D.	N.D.	N.D.	1000
Bis(2-ethylhexyl) Phthalate(DEHP)	mg/kg	50	N.D.	N.D.	N.D.	N.D.	1000
Diisobutyl phthalate(DIBP)	mg/kg	50	N.D.	N.D.	N.D.	N.D.	1000

Appendix

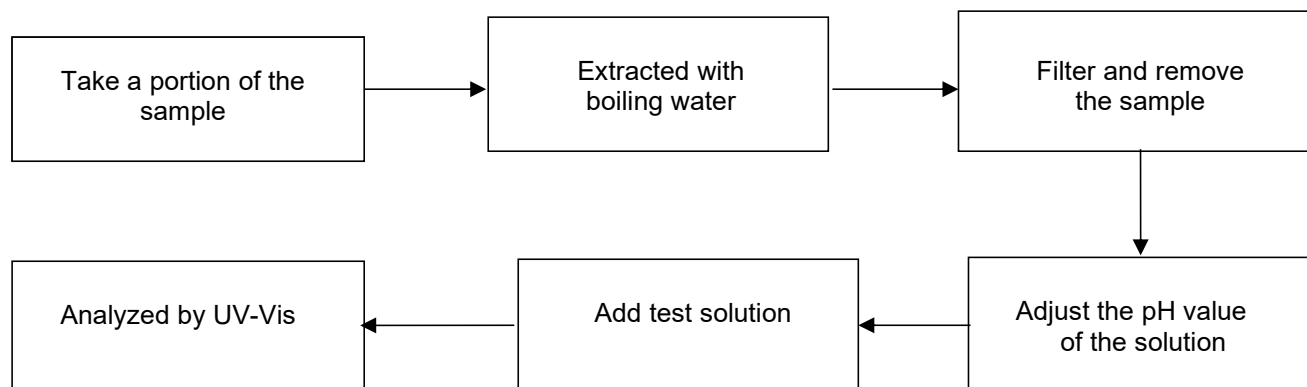
1. Test Flow chart for Cd/Pb /Hg content

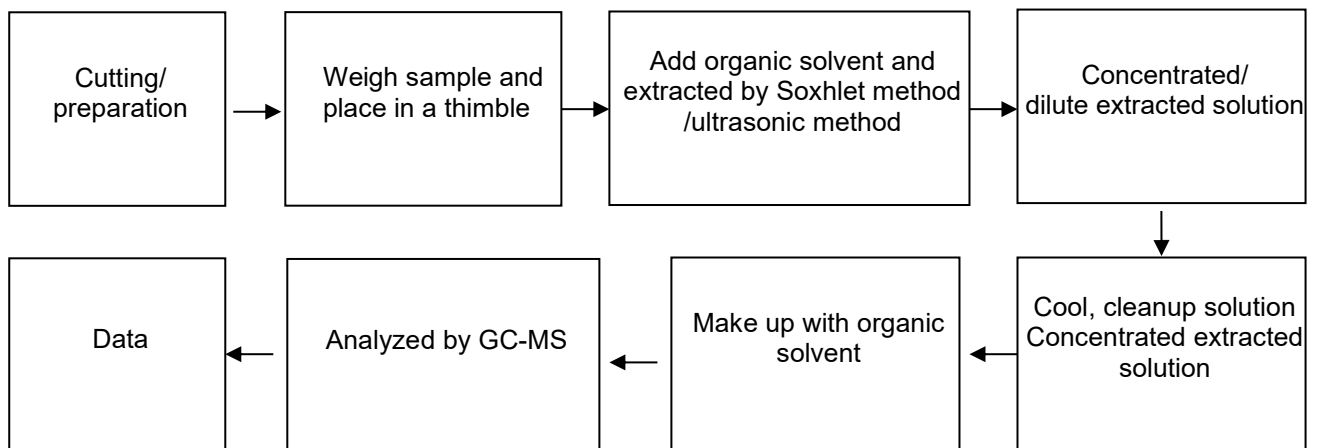


2. Test Flowchart for Cr⁶⁺ content (For non-metal material)



Test Flowchart for Cr⁶⁺ content (For metal material)



3. Test Flow chart for PBBs & PBDEs & DBP & BBP & DEHP & DIBP content

Photos

Photo 1 Overall view

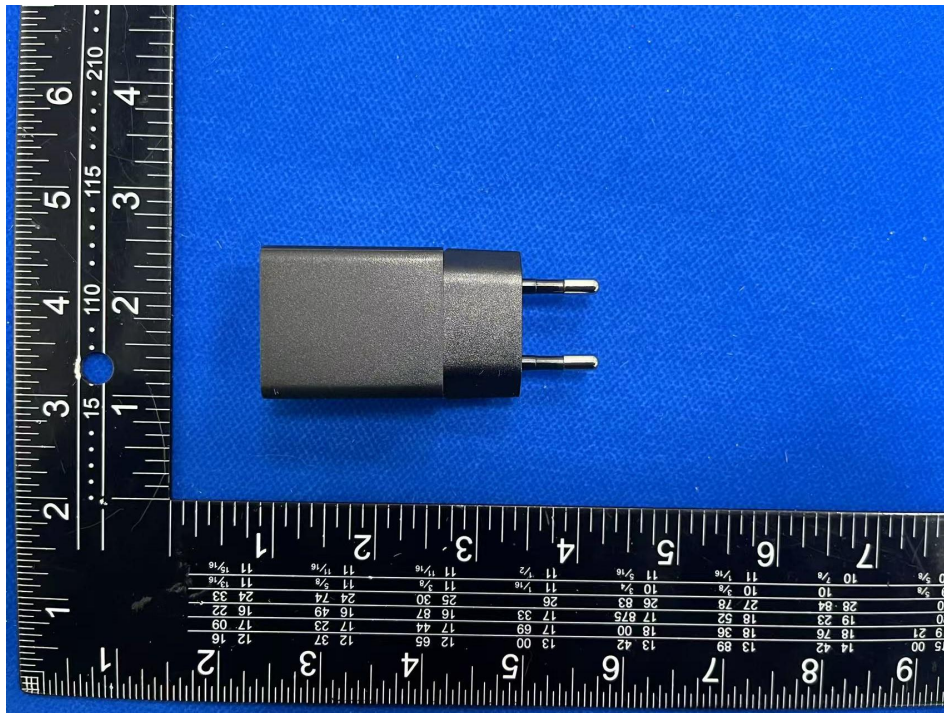


Photo 2 Overall view

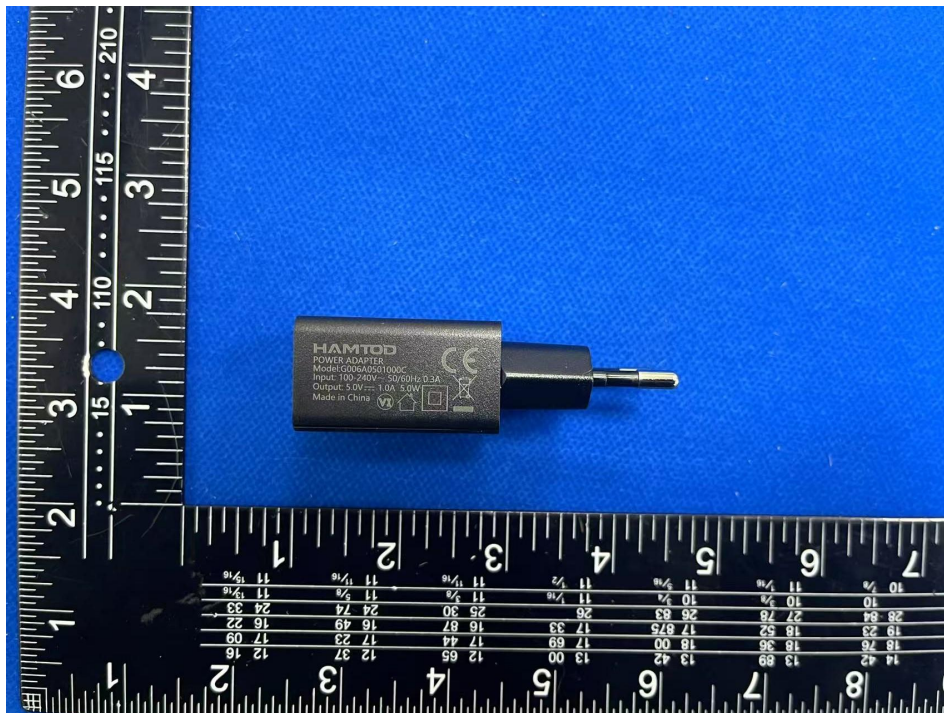


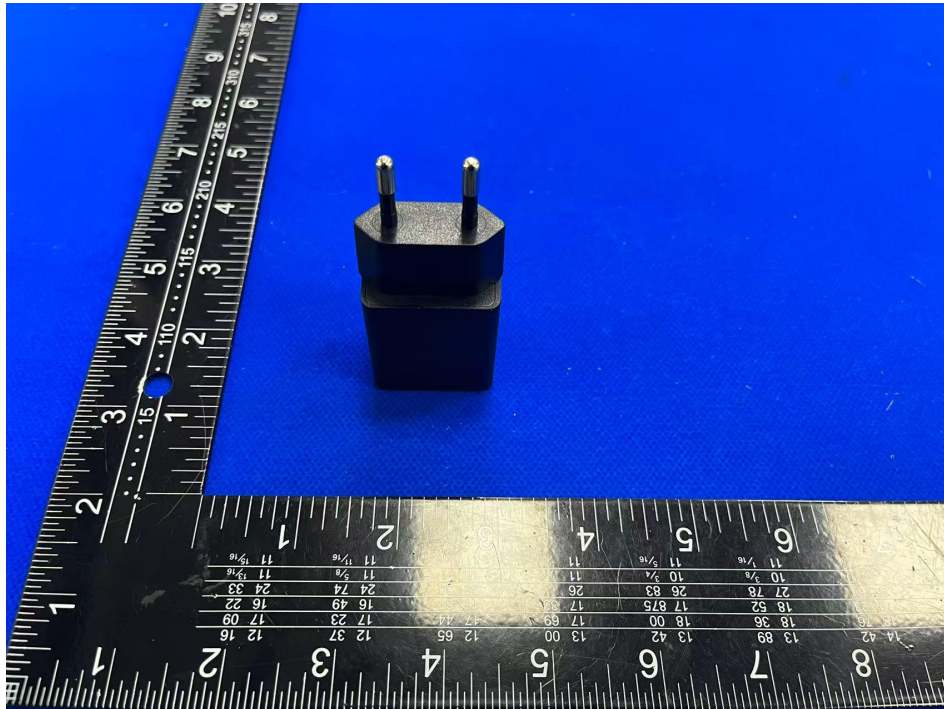
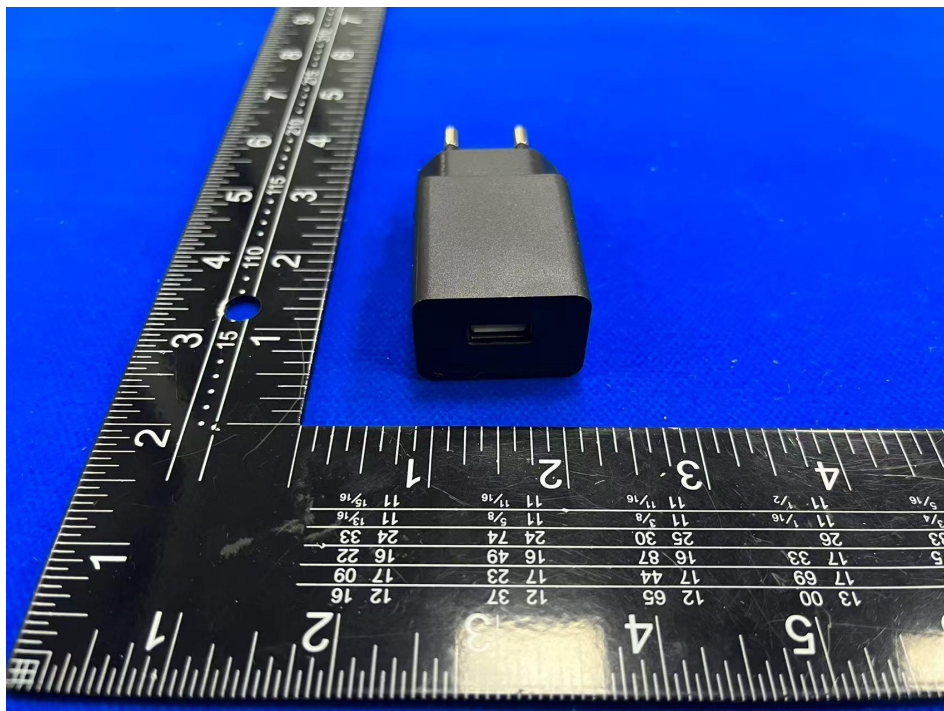
Photo 3 Overall view**Photo 4 Overall view**

Photo 5 PCB view

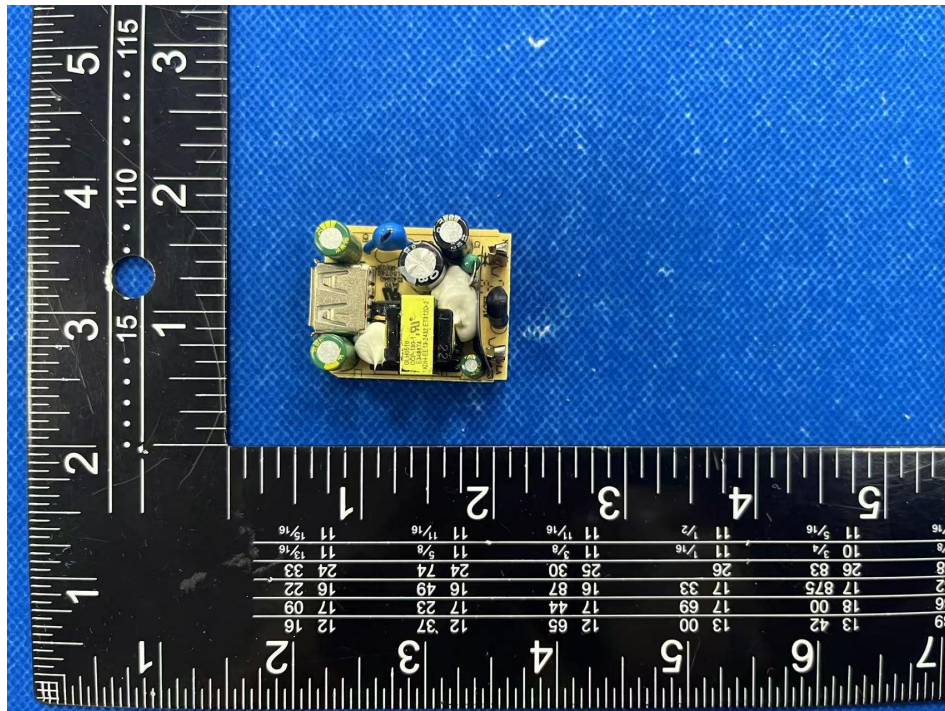


Photo 6 PCB view

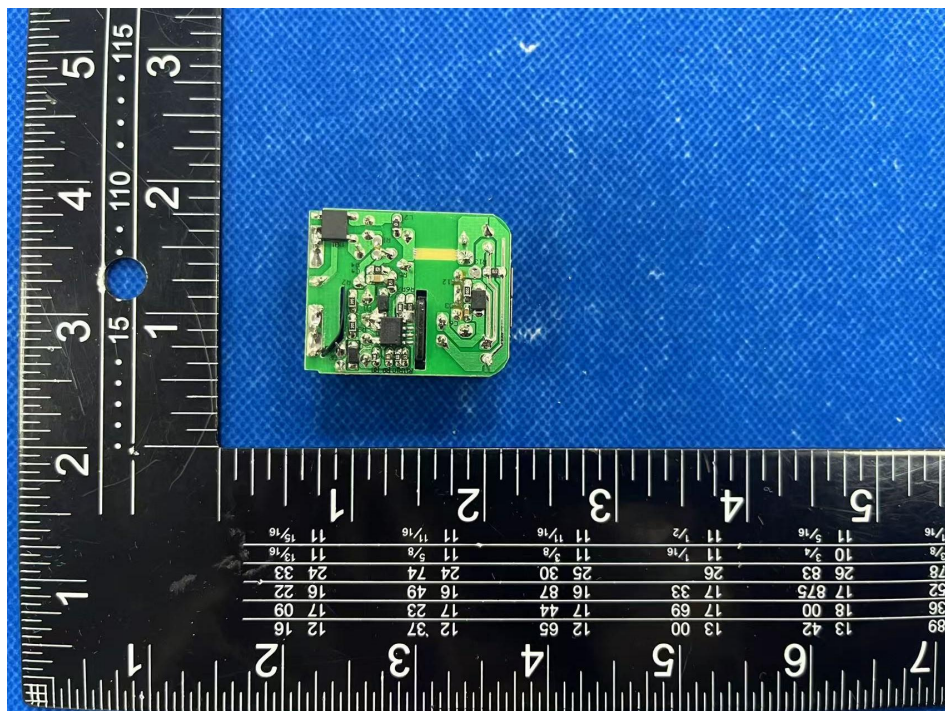
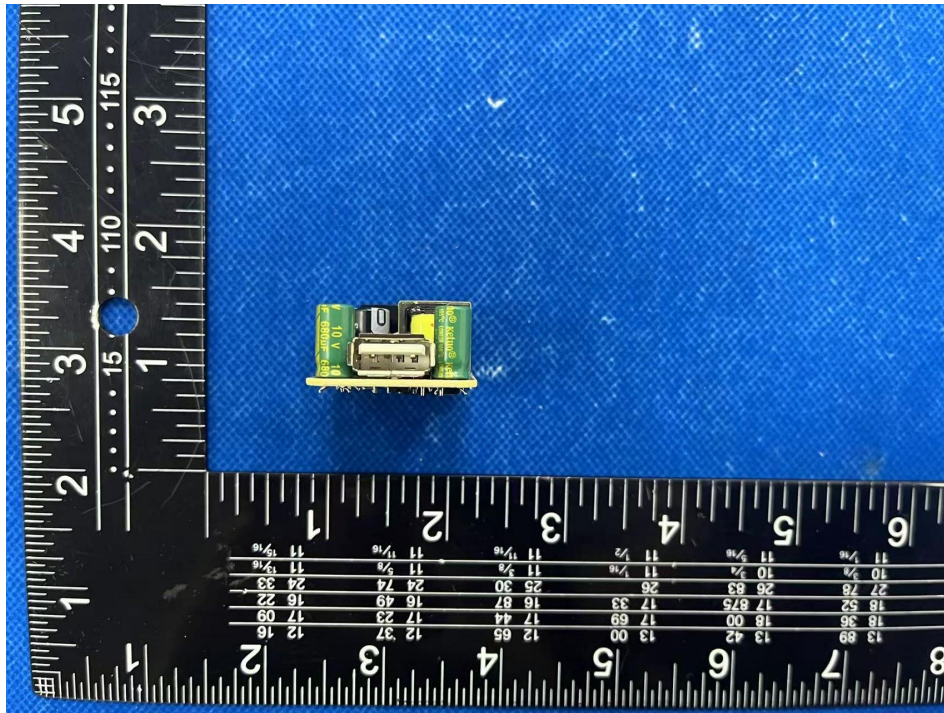


Photo 7 PCB view**END OF REPORT**